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REPORT

on

COMPONENT - Wiring, Printed - Component

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DESCRIPTION

PRODUCT COVERED:

USR - Multilayer printed wiring board. See Table IA for Type Designations.

CNR - Multilayer printed wiring board. See Table IA for Type Designations.

TECHNICAL CONSIDERATIONS (NOT FOR FIELD REPRESENTATIVE'S USE):

USR - United States Recognized.

CNR - Canadian Standards Recognized.

Use - The boards are for use only in electrical equipment where the acceptability of the combination has been determined by UL LLC.

CONDITIONS OF ACCEPTABILITY - The following are among the considerations to be made in judging the suitability of the boards in the end product.

1. Pattern Limits - Conductor pattern limits are specified in Parameter Profile Indices (Table IA) and Silver Conductor Limitations (Table IB). The edge conductor width and midboard conductor width specified in Table IA are the minimum acceptable widths. The maximum area diameter is the maximum unpierced conductor area of any pattern, typically a ground plane, and is determined by the largest circle that can be inscribed within the conductor. The minimum separation between silver conductors of different potential is specified in Table IB. Flame Only boards are not evaluated to determine conductor pattern limits and shall be considered during the end product evaluation.
2. Surface Mount Technology - Printed wiring boards with circuitry using surface mount technology shall be Recognized with an assembly solder process. "Yes" is used in Table IA to indicate the printed wiring board Types that may contain surface mount technology. "No" is used to indicate the printed wiring board Types that cannot contain surface mount technology.

CONDITIONS OF ACCEPTABILITY (Continued) -

3. Assembly Solder Process and Solder Limits - Assembly solder process (ASP) and solder limits are a critical parameter for the printed wiring board and are used as preconditioning for the flammability classification and the maximum operating temperature (MOT). Assembly solder process and solder limits are profile(s), temperature(s) and time(s) representing the anticipated PWB production component assembly process(es). The component assembly solder process specified in Table IA shall not exceed the indicated peak temperature on the printed wiring board surface, dwell-time exposure and/or number of cycles during reflow, wave, dip, or an equivalent soldering operation. Printed wiring boards with circuitry using surface mount technology shall be evaluated to the assembly solder process requirements. If the printed wiring board does not contain surface mount technology, either assembly solder process or solder limit requirements shall be evaluated. If Table IA indicates both ASP and solder limits for a single Type, then both ASP plus the solder limits have been evaluated.

The UL 796 standardized assembly soldering profiles are not prescriptive and may not represent the exact component assembly solder process. The board maximum surface temperature measured during the assembly solder process determines the peak temperature. The number of cycles for all soldering processes when the soldering is done in different steps shall not be exceeded. The cumulative time is not controlled if the number of soldering cycles is not exceeded. Assembly solder process Recognition may represent reflow, wave and/or selective soldering or other equivalent soldering techniques if the number of cycles is not exceeded. The solder limits represent wave or selective soldering techniques. The assembly solder process and solder limits do not apply to hand soldering.

4. Maximum Operating Temperature (MOT) - The maximum continuous use temperature the board is exposed to in the end product shall not exceed the value specified in Table IA with consideration to solder limits and ASP during the assembly soldering process. The maximum operating temperature is not evaluated for Flame Only boards and shall be considered during the end product evaluation.

CONDITIONS OF ACCEPTABILITY (Continued) -

5. Flammability - The flammability classification, with consideration to solder limits and ASP during the assembly soldering process, for the board is indicated in Table IA. The classification is based on samples tested in accordance with UL 94 and CAN/CSA-C22.2 No. 0.17 test methods with and without nonmetallic permanent coatings (such as solder resist). Only Permanent Coatings (ex: solder resist, hole plugging material, decorative coating, overcoat and/or undercoat) specified in the Permanent Coatings Table IIIA may be employed. Unless specified in Table IIIA, multiple layers of permanent coatings may not be employed. If the board assembler or end product manufacturer applies any permanent coating, the effect on the flammability of the board is to be considered in the end product evaluation. Marking ink and flux are not considered a permanent coating. Non-flame and HB rated Types may be coated with any permanent coating.
6. Silver Conductors - The minimum clearance and creepage distance between any two silver conductors of different potential must not be less than that indicated in Table IB. The silver conductors have been found suitable only for circuits that do not require a dielectric strength potential greater than that indicated between adjacent parts and conductors. The maximum voltage applied between any two silver conductors of different potential shall not exceed that listed in Table IB. Reference to silver conductors includes silver, electroless or electroplated silver plating, or silver paste, for purposes of this report, unless otherwise indicated. Immersion Silver, Tin-Silver-Copper [Sn-Ag-Cu(SAC)] alloy, other silver containing tertiary alloys, and Tin-Silver (SnAg) alloy coated conductors do not require a silver migration evaluation. Flame Only boards are not evaluated to determine if silver conductors are present on the board, and the effect of silver conductors on the board shall be considered during the end product evaluation.
7. Direct Support of Current-Carrying Parts - Printed wiring boards used as a dielectric barrier and/or substrate for conductors of opposite polarity are identified to meet direct support requirements (DSR) for current carrying parts at 120 Vrms or less and 15 A or less. Boards evaluated to determine the dielectric material(s) meets the UL 796 minimum levels for direct-support of current carrying parts are identified in Base Materials Table IIA to enable the OEM to select appropriate printed wiring boards for the end use application. Flame Only boards are not evaluated to determine direct support and shall be considered during the end product evaluation.

CONDITIONS OF ACCEPTABILITY (Continued) -

8. Comparative Tracking Index (CTI) - The CTI is expressed as that voltage which causes tracking on a material after 50 drops of 0.1 percent ammonium chloride solution has fallen on the material. Results of testing the nominal 3 mm thickness are considered representative of the material's performance in any thickness. Boards shall be assigned a performance level category (PLC) for CTI based on the PLC assigned to the material in accordance with UL 746E. The CTI is identified in Table IIA and shall be used by the OEM in selection of PWBs for applications in which the CTI rating is significant, such as for decreased clearance and creepage distances. Flame Only boards are not evaluated to determine CTI and shall be considered during the end product evaluation. For CNR, the actual CTI voltage values are indicated in Table IIA.

CTI Range Tracking Index (TI in Volts)	Assigned PLC
600 and greater	0
400 and up to 600	1
250 and up to 400	2
175 and up to 250	3
100 and up to 175	4
Less than 100	5

9. Voltage Rating - No voltage rating is assigned. The suitability of the dielectric base material(s) as insulation between different potential conductors and between these conductors and dead-metal parts shall be considered in the end product evaluation. See Table IB for silver voltage limitations and Table IIA for base material identification.
10. Mechanical Strength - The adequacy of the board for the support and replacement of components shall be considered in the end product evaluation.
11. EMI Shielding Films - The adequacy of EMI shielding has not been evaluated for shielding properties and shall be considered in the end product evaluation.
12. Embedded Components - The function of the embedded component shall be considered during the end product evaluation.

CONDITIONS OF ACCEPTABILITY (Continued) -

13. Cemented Joint - For multilayer printed wiring boards, the path between conductors on the same internal layer surface is filled with insulating material and the two non-conductive insulating layers are bonded together to form a cemented joint. A cemented joint working voltage and distance through insulation shall be used by OEM in selection of PWBs for applications in which the cemented joint is significant, such as for decreased clearance and creepage distances. See Cemented Joint Limitations in Table IC to determine if the cemented joint construction has been evaluated for the printed wiring board Type. Tests were conducted in accordance with UL 62368-1.
14. Flammability Only Boards - Printed wiring boards investigated for flammability characteristics only. The bond strength of conductors, delamination and blistering of base materials, direct support, CTI and/or the silver conductor limitations shall be considered during the end product evaluation.
15. Printed Wiring Board construction modification - For any changes in the construction, such as addition, deletion, or change in material, the requirements for printed wiring boards in UL 796 shall be followed.
16. Other Considerations - The following items shall be considered for insertion into the end product report:
 - A. Minimum required spacing between conductors of different potential and between the conductors and dead-metal parts. Cupping, twisting, bowing and/or warping of the board has not been evaluated.
 - B. Minimum required dielectric insulation thickness (distance through) between conductor layers has not been evaluated regarding electric strength properties.
 - C. Pattern Limits. The narrowest conductor width shall not be less than the indicated minimum midboard or edge conductor width depending upon operating temperature and/or ampacity conditions, as indicated in the end product report. For Flame Only boards, the minimum width conductors have not been established.
 - D. Thickness or weight of conductors.
 - E. Assembly Solder Process (ASP) and/or Solder limits.
 - F. The overall board dimensions.
 - G. Identification marking(s).
 - H. For flammability classification, identification of coatings applied by the assembler, end product, or user.

GENERAL CHARACTERISTICS:

The printed wiring boards must meet the pattern limits, solder limits and/or assembly solder process given by Engineering Considerations and Table IA and IB.

The printed wiring boards are multilayer in construction, comprised of alternate layers of the laminates and prepregs (bonding sheets) indicated in Table IIA. Individual laminates and prepregs sheet thicknesses shall not be used at thicknesses less than those indicated in Table IIA.

The laminates are to be used in conjunction with their respective prepregs. Different manufacturer's materials shall not be used in the same board, unless otherwise specified. Unless more than one grade is specified for the same board, different grades of the same material manufacturer shall not be used.

The overall thickness of the finished board shall be equal to or greater than the minimum indicated in the "Total Bld-Up Thk" column in Table IIA excluding conductors.

The printed wiring boards are fabricated with a solid external copper sheet in the thicknesses indicated in Table IIA bonded to one or both sides of the internal or external dielectric materials, unless otherwise indicated.

The printed wiring boards are fabricated with permanent coatings (solder resist, secondary coatings, etc) applied to the external surface as indicated in Table IIIA. Hole plugging materials are used to fill the board vias as described in the manufacturing process and Table IIIA.

There shall be no changes, additions or substitutions made by the manufacturer in the printed wiring board production as described without prior written clearance from UL LLC.

Marking - See Section General.

TABLE IA - PARAMETER PROFILE INDICES

Type	Pattern Limits			Surface Mount Technology Yes/No	ASP Conditions	Assembly Solder Process (ASP)		Solder Limits		Max Oper Temp (C)	Flame Class	USR/CNR
	Min Cond Width (mm)	Min Edge Cond Width (mm)	Max Area Diam (mm)			Temp (C)	Cycles	Max Temp (C)	Max Time (sec)			
JFG-04	0.075	76.2	0.075	Yes	ASP 1	260	3	288	20	130	V-0	USR/CNR

Notes:

ASP 1 - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

USR - United States Recognized

CNR - Canadian Standards Recognized

TABLE IB - SILVER CONDUCTOR LIMITATIONS

Type	Silver Conductor Materials Present (Yes/No)	Min. Spacing Between Adjacent Silver Conductors of Different Potential (mm)	Maximum Voltage Withstood Between Silver Conductors (V dc)
JFG- 04	Yes, Silver Immersion	Not Applicable	Not Applicable

Note: See Conditions of Acceptability for types of silver conductors that do not require silver migration evaluation.

TABLE IC - Cemented Joint Limitations

Type (Note 1)	Minimum Distance Through Insulation (mm)	Electric Strength Test Voltage (Table 5B IG V X 1.6) (Vac)	AC Mains or DC Mains
Reserved for future use.			

Note 1 - Only board types listed in Table IC have had the Cemented Joint construction evaluated.

TABLE IIA - BASE MATERIALS

Type	Base Material (Recognized Component QMTS2)								Total Bld- Up Thk (mm)	Min Cond Thk# (mic)	Max Cond Thk# (mic)	Mfg Proc	Meets DSR	CTI (PLC/V)
	Individual Laminate Sheet				Individual Bonding Sheet									
	UL/ ANSI Grade	+ UL File	Grade	Min Thk (mic)	UL/ ANSI Grade	+ UL File	Grade	Min Thk (mic)						
JFG-04	FR-4.0	E109769	S1141, S1141-4, S1141 150, S1141 170, S1151	50	FR-4.0	E109769	S0401, S0401-4, S0401 150, S0401 170, S1151B	50	0.38	E:12	E:102 I:102	E	YES	3/175
	FR-4.0	E109769	S1000M, S1000H, Autolad1	50	FR-4.0	E109769	S1000MB, S1000HB, Autolad1B	50	0.38	E:12	E:102 I:102	E	YES	3/175
	FR-4.1	E109769	S1145, S1150G, S1125, SI055W	50	FR-4.1	E109769	S1145B, S1150GB, S1125B, SI055WB	30	0.38	E:12	E:102 I:102	E	YES	1/400
	FR-4.0	E109769	S1000-2M, Autolad3	50	FR-4.0	E109769	S1000-2MB, SP170M, Autolad3B	50	0.38	E:12	E:102 I:102	E	YES	3/175
	FR-4.0	E109769	S1600L	50	FR-4.0	E109769	S1600LB	50	0.38	E:12	E:102 I:102	E	YES	0/600
	FR-4.1	E109769	S1151G	50	FR-4.1	E109769	S1151GB	50	0.38	E:12	E:102 I:102	E	YES	0/600
	FR-15.1	E109769	S1170G, S7045GH	50	FR-15.1	E109769	S1170GB, S7045GHB	30	0.38	E:12	E:102 I:102	E	YES	3/175

+ - See Table IIB for Base Material Manufacturer/File

- I: Internal copper thickness; E: External copper thickness

TABLE IIB - Base Material Manufacturer/File (Refer to TABLE IIA)

UL File	Manufacturer
E109769	Shengyi

TABLE IIIA - PERMANENT COATINGS (RECOGNIZED COMPONENT - QMJU2)

Types	Process	Solder Resists +
JFG-04	E	1,2,3,4

Types	Process	Coating Combinations (Order of Application) +
JFG-04	E	A/1,B/2,C/3,D/4

+ - See Table IIIB for Permanent Coating Grade, UL File, and Manufacturer

TABLE IIIB - PERMANENT COATINGS GRADE, UL FILE and MANUFACTURERS

No.	Solder Resist		
	Grade	UL File	Manufacturer
1.	KSM-S6189/KSM-19 (All)	E189612	Guangzhou Kuangshun
2.	PM-600/H-60 (NC, GN, BK)	E343546	Guangdong Coants
3.	SR-500/CA-66 (All)	E466073	China S.M
4.	PSR-4000DE/CA-40DE (GN,BK,BL)	E69262	Taiyo

No.	Hole Plugging Material		
	Grade	UL File	Manufacturer
A.	KSM-S6189/KSM-19 (All)	E189612	Guangzhou Kuangshun
B.	PM-600/H-60 (NC, GN, BK)	E343546	Guangdong Coants
C.	SR-500/CA-66 (All)	E466073	China S.M
D.	PSR-4000DE/CA-40DE (GN,BK,BL)	E69262	Taiyo

MANUFACTURING PROCESS:

1. Machining, cleaning, rinsing, air-drying and similar operations may be performed by the manufacturer but are not required to be listed in the following process description(s).
2. If not listed in the process description(s), temperatures equal to or above 100C or above the MOT of the board Type, whichever is greater, shall not be used in the following process description(s).
3. Conductive coatings and/or platings used in the production of the printed wiring board Type(s) shall be specified in the manufacturing process description(s).
4. Any of the steps in the following process description(s) may be omitted from the manufacturing process at the manufacturer's option unless the process step is noted as a MUST step.
5. There shall be no changes, additions or substitutions by the manufacturer to the following manufacturing process(es) without prior written clearance from UL LLC.
6. Process steps can be performed by an outside facility (subcontractor, multisite processor or alternate manufacturing location). Documentation is to be provided by the original manufacturing location to the outside facility (see Appendix D for the service/work (traveler) instructions). This documentation and the finished boards shall be returned only to the original manufacturer.

Critical steps (including, but not limited to, temperatures equal to or above 100C or the MOT, whichever is greater) performed by an outside facility (subcontractor) shall be indicated in the Process description by the footnote "++". The subcontractor shall be indicated in the Section General. The alternate manufacturing location shall be indicated in the Authorization Page or Addendum.

Non-critical steps (including, but not limited to, temperatures below the MOT or 100C) may be performed by any outside facility (multisite processor).

If the outside facility is procuring materials directly from the material vendor, the outside facility shall be documented as a subcontractor.

PROCESS (ES) :

See next page(s).

Process E:

1	May cut boards.
2	May bake at 190°C maximum for 360 minutes maximum.
3	May drill and debur board
4	May electroless copper plate or electroplate copper plate.
5	May electroless plate copper over through holes/ fill holes or entire board
6	May plug hole using hole plugging material. And then Boards may be dried at 190°C maximum for 6 hours maximum. (Hole plugging materials used in this step must be encapsulated by copper).
7	May electroless copper plate or electroplate copper plate.
8	May image for innerlayer; laminate dry film or wet film at 150°C maximum for 60 minutes maximum.
9	May etch using any etchant except chromic/sulfuric.
10	May strip etch resist, rinse and dry.
11	May apply black oxide treatment. brown treatment.
12	May dry at 160°C maximum for 120 minutes maximum.
13	May laminate boards at 260°C maximum for 360 minutes maximum at a lamination pressure of 500PSI maximum.
14	May dry at 160°C maximum for 120 minutes maximum.
15	May cut, drill and debur boards.
16	May electroless copper plate.
17	May scrub boards.
18	May print pattern by silk screening or laminate dry-film at 160°C maximum for 120 minutes maximum.
19	May electroplate copper, then electroplate tin-lead.
20	May strip plating resist.
21	May etch using any etchant except chromic/sulfuric.
22	May strip tin-lead.
23	May plate with nickel/gold.
24	May plug hole using hole plugging material and cure at 180 °C maximum for 120 minutes maximum,
25	Non-flame and HB rated types may be coated or hole plugged with any solder resists. V rated types may be coated or hole plugged with the resists indicated in the following pages. Board may then be dried at 180°C maximum for 120 minutes maximum.
26	May apply marking ink, and cure at 180°C maximum for 120minutes maximum.
27	May apply Peelable solder mask, and cure at 180°C maximum for 90 minutes maximum.
28	May apply solder using hot air solder level at 288°C maximum for 20 Second maximum.
29	May electroplate Ni/Au or Ni/PdAu on contact fingers or entire pattern.
30	May immersion Ni/Au, Ag, Sn. Ni/Pd Au
31	May perform punching or routing.
32	May wash boards and dry at 150oC maximum for 120 minutes maximum.

Process E: (con't)

33	May press and bake for curved board at 260°C for 240 minutes maximum at a lamination pressure of 260PSI maximum.
34	May apply flux or OSP.
35	May print blue adhesive and cure at 180°C maximum for 90 minutes maximum. The blue adhesive will be pulled away.
36	No other plating operations performed and no other temperatures over 100°C or the maximum operating temperature of the board, whichever is greater, are encountered.